

DA2J101

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Small reverse current I_R
- Short reverse recovery time t_{rr}
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: A1

■ Packaging

DA2J10100L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Maximum peak reverse voltage	V_{RM}	80	V
Forward current	I_F	100	mA
Peak forward current	I_{FM}	225	mA
Non-repetitive peak forward surge current *1	I_{FSM}	500	mA
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1: $t = 1$ s

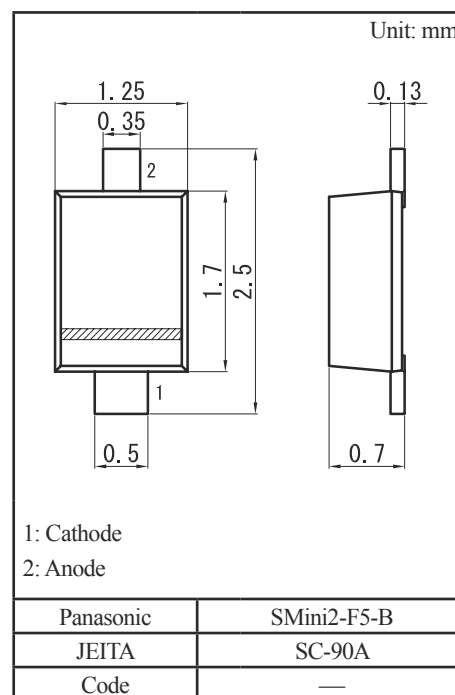
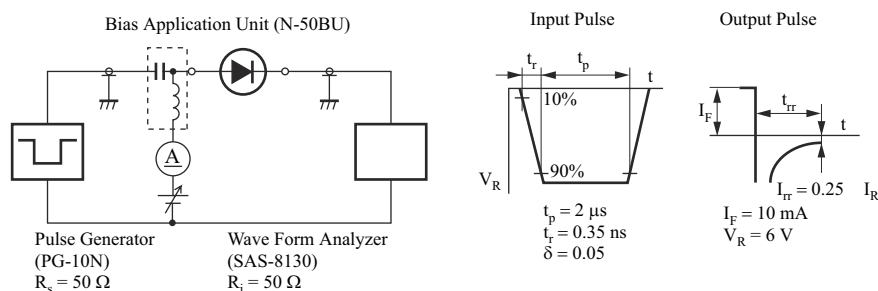
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

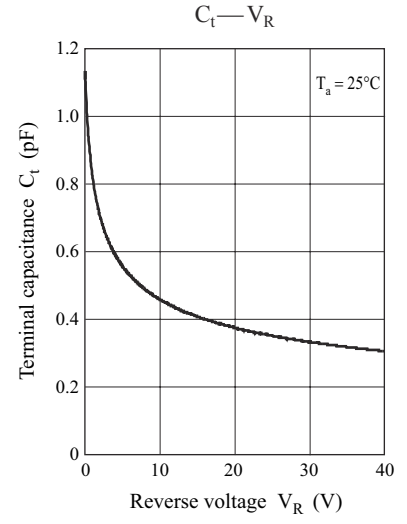
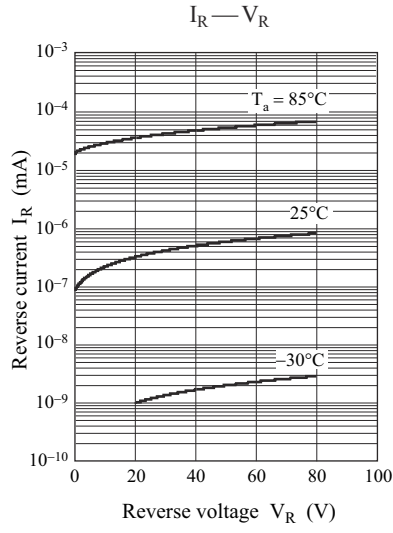
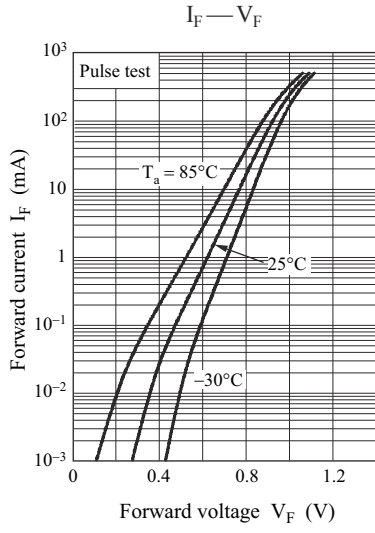
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100$ mA		0.92	1.20	V
Reverse voltage	V_R	$I_R = 100$ μA	80			V
Reverse current	I_R	$V_R = 80$ V			100	nA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz			1.2	pF
Reverse recovery time *1	t_{rr}	$I_F = 10$ mA, $V_R = 6$ V, $I_{rr} = 0.25 \times I_R$			3	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz

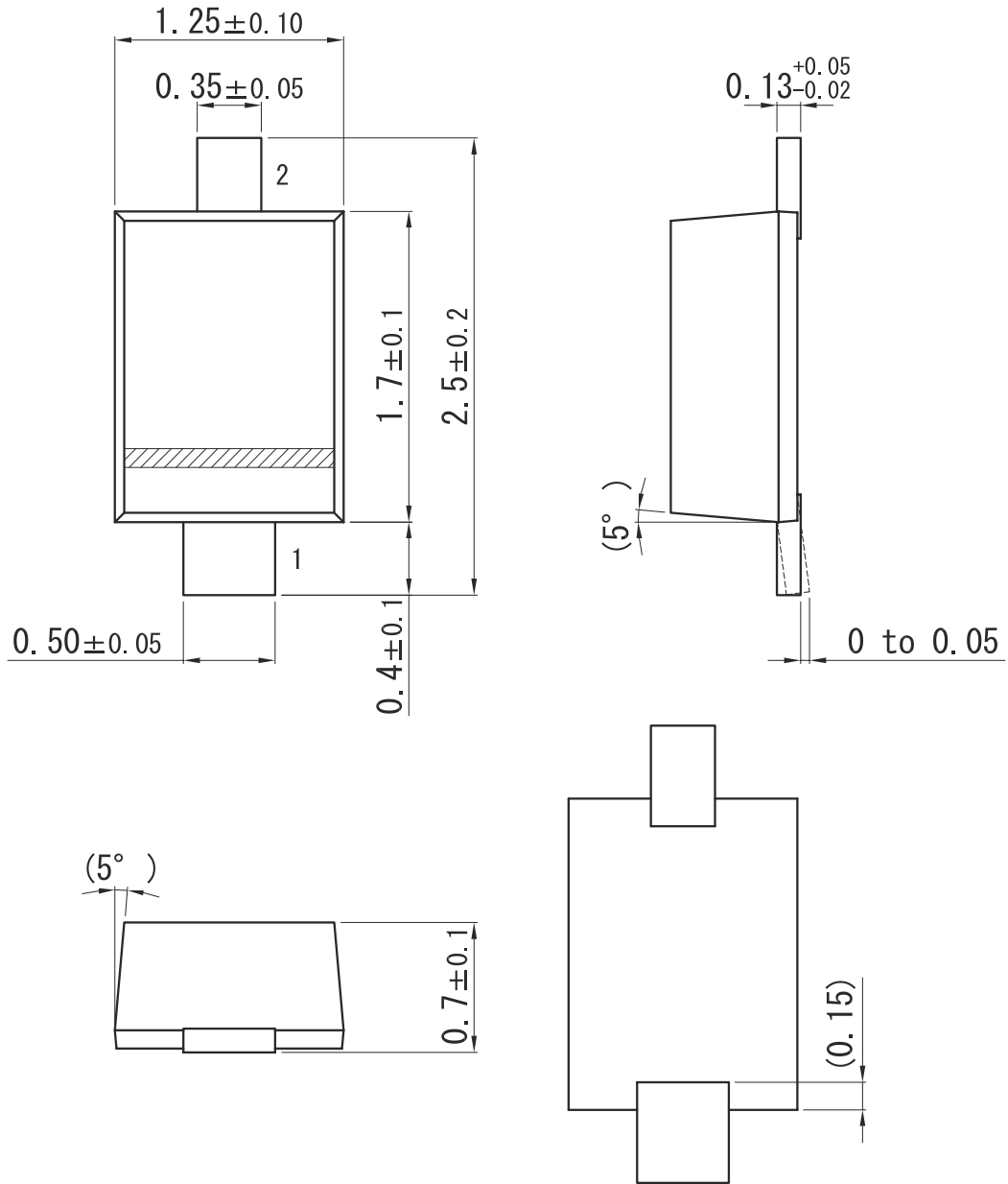
3. *1: t_{rr} measurement circuit



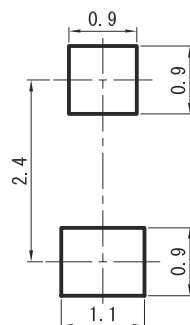


SMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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